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Part Number:

0736562000

Status:

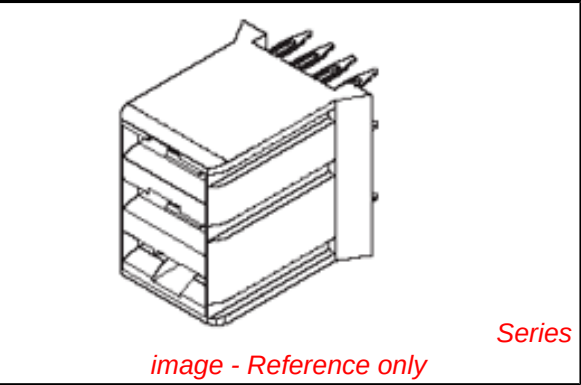
Active

Overview:

[hdm](#)

Description:

2.00mm (.079") Pitch HDM® Board-to-Board Backplane Power Module, Vertical, SMC, Power Receptacle, 3 Circuits, Gold (Au) 0.76µm (30µ")



Documents:

[Drawing \(PDF\)](#)

[RoHS Certificate of Compliance \(PDF\)](#)

[Product Specification PS-73670-9999 \(PDF\)](#)

General	
Product Family	Backplane Connectors
Series	73656
Application	Backplane
Comments	Backplane Power Module
Component Type	Power Header
Overview	hdm
Product Name	HDM®
Style	N/A
Physical	
Circuits (Loaded)	3
Circuits (maximum)	3
Color - Resin	Black
Durability (mating cycles max)	250
First Mate / Last Break	No
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Beryllium Copper
Material - Plating Mating	Gold
Material - Plating Termination	Gold
Material - Resin	High Temperature Thermoplastic
Number of Columns	1
Number of Pairs	Open Pin Field
Number of Rows	3
Orientation	Vertical
PC Tail Length (in)	0.138 In
PC Tail Length (mm)	3.50 mm
PCB Locator	No
PCB Retention	None
PCB Thickness Recommended (in)	0.138 In
PCB Thickness Recommended (mm)	3.50 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Pitch - Term. Interface (in)	0.079 In
Pitch - Term. Interface (mm)	2.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	2
Plating min: Termination (µm)	0.05
Polarized to PCB	No
Stackable	No
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole - Compliant Pin

EU RoHS

ELV and RoHS

Compliant

REACH SVHC

Contains SVHC: No

Halogen-Free

Status

Not Reviewed

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com

For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

73656Series

Mates With

73651 HDM® Board-to-Board Daughterboard Power Module

Electrical

Current - Maximum per Contact	15A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	500V AC

Material Info

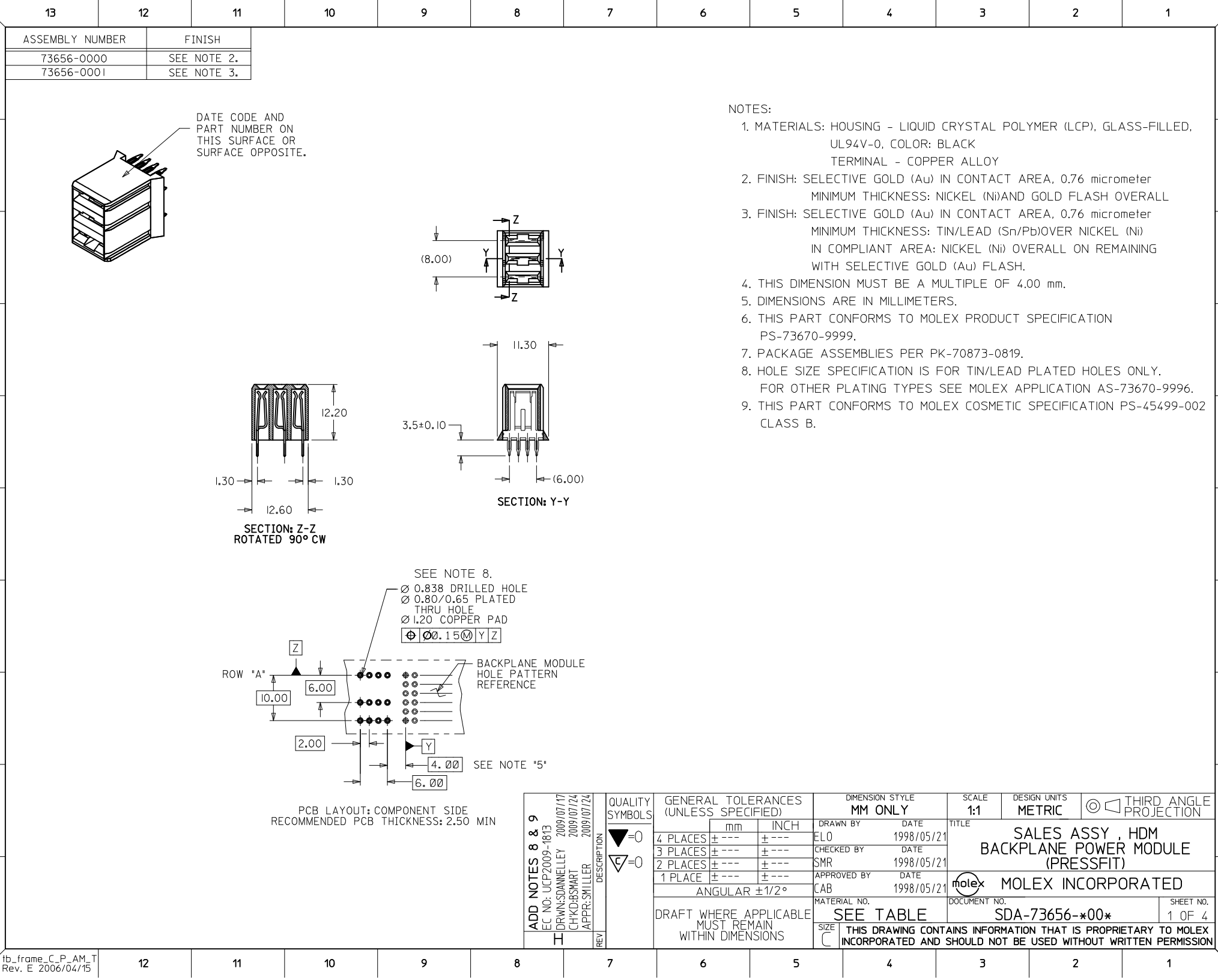
Reference - Drawing Numbers

Application Specification	AS-73656-1998
Packaging Specification	PK-70873-0819
Product Specification	PS-73670-9999
Sales Drawing	SDA-73656-*00*

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This document was generated on 05/14/2010

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F

E

D

C

B

A

F

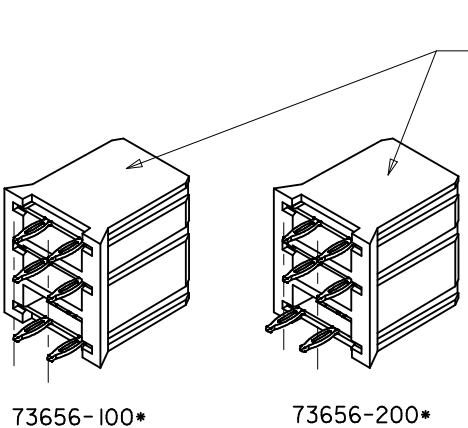
E

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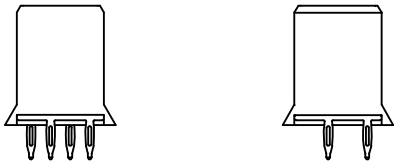
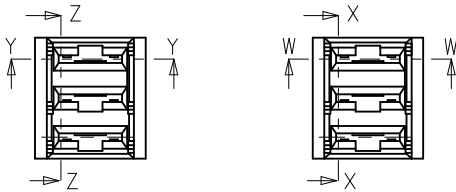
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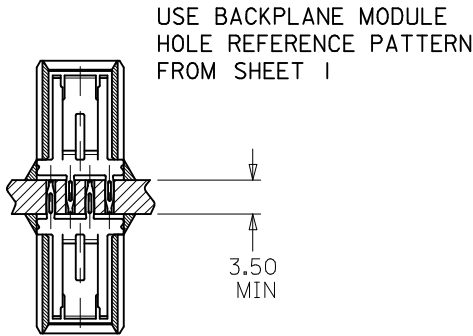
DATE CODE AND
PART NUMBER ON
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MIDPLANE OPTION

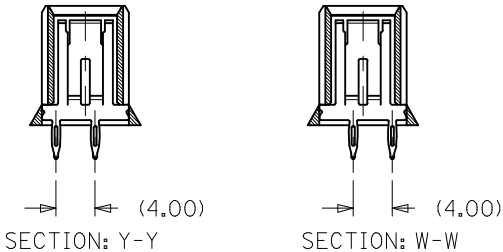
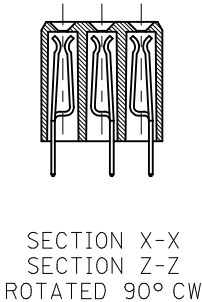
ASSEMBLY NUMBER	FINISH (SEE SHT 1)
73656-1000	SEE NOTE 2. (GOLD TAILS)
73656-2000	
73656-1001	SEE NOTE 3. (TIN/LEAD TAILS)
73656-2001	



73656-200* 73656-100*



BACK-TO-BACK
MOUNTING APPLICATION



SEE SHEET 1 EC NO: UCP2009-1813 DRWN:SDANIELLEY 2009/07/17 CHKD:BSMART 2009/07/24 APPR:SMILLER 2009/07/24 REV	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION			
		 =0  =0		mm	INCH	DRAWN BY	DATE	TITLE SALES ASSY , HDM BACKPLANE POWER MODULE (PRESSFIT)  MOLEX INCORPORATED				
			4 PLACES	± ---	± ---	ELO	1998/05/21					
			3 PLACES	± ---	± ---	CHECKED BY	DATE					
			2 PLACES	± ---	± ---	SMR	1998/05/21					
			1 PLACE	± ---	± ---	APPROVED BY	DATE					
		ANGULAR ±1/2°				CAB	1998/05/21	DOCUMENT NO. SDA-73656-*00* SHEET NO. 2 OF 4				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				MATERIAL NO.					SEE TABLE	
						SIZE B	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

ASSEMBLY NUMBER

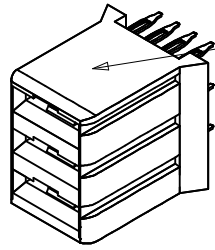
FINISH (SHT I)

73656-5000

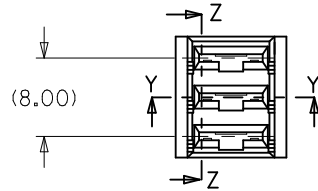
SEE NOTE 2.

73656-5001

SEE NOTE 3.



DATE CODE AND
PART NUMBER ON
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SURFACE OPPOSITE.



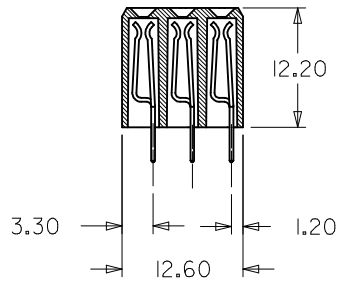
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11.30

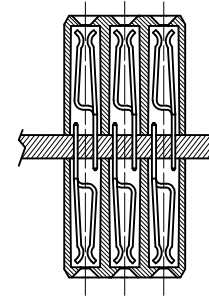
3.5±0.10

(6.00)

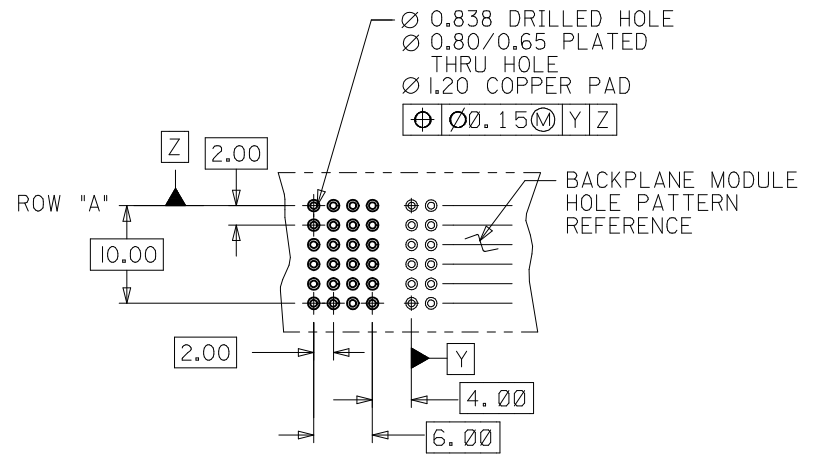
SECTION: Y-Y



SECTION: Z-Z
ROTATED 90° CW



2.36 MIN



SEE SHEET 1 EC NO: UCP2009-1813 DRWN:SDANIELLEY 2009/07/17 CHKD:BSMART 2009/07/24 APPR:SMILLER 2009/07/24	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽C=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
				mm	INCH	DRAWN BY	DATE	TITLE SALES ASSY , HDM BACKPLANE POWER MODULE (PRESSFIT)  MOLEX INCORPORATED	
			4 PLACES	± ---	± ---	ELO	1998/05/21		
			3 PLACES	± ---	± ---	CHECKED BY	DATE		
			2 PLACES	± ---	± ---	SMR	1998/05/21		
			1 PLACE	± ---	± ---	APPROVED BY	DATE		
ANGULAR ±1/2°		CAB	1998/05/21	DOCUMENT NO.		SHEET NO. 3 OF 4			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		SDA-73656-*00*					
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

ASSEMBLY NUMBER

FINISH

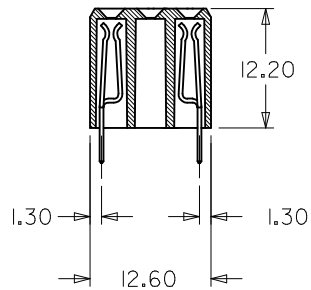
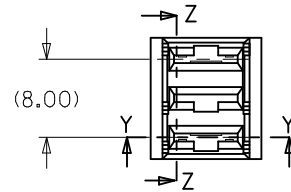
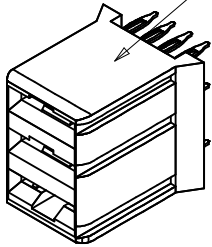
73656-0180

SEE NOTE 2.

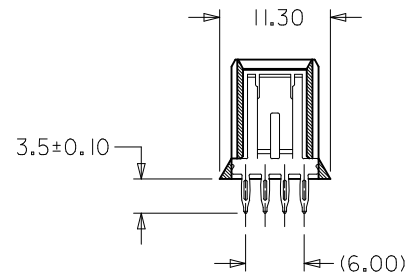
73656-0181

SEE NOTE 3.

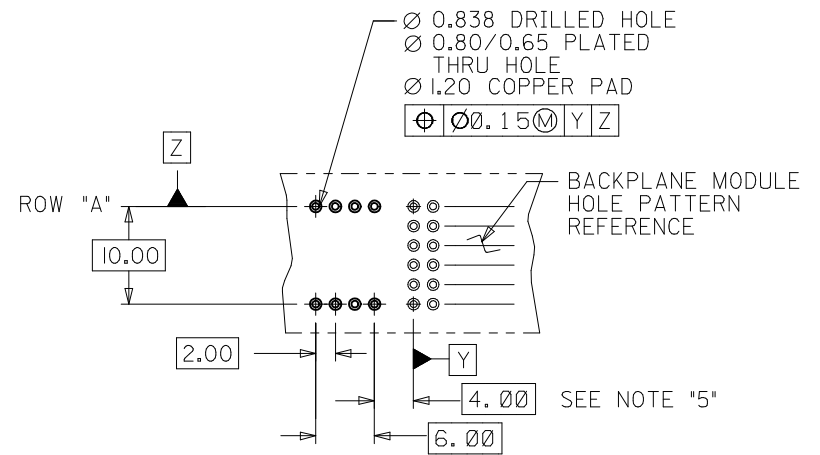
DATE CODE AND
PART NUMBER ON
THIS SURFACE OR
SURFACE OPPOSITE.



SECTION: Z-Z
ROTATED 90° CW

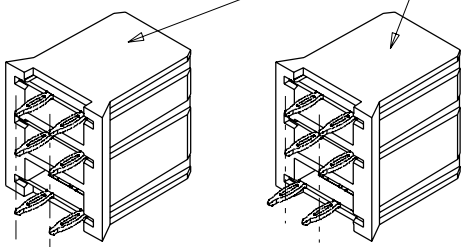


SECTION: Y-Y



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN

SEE SHEET 1 EC NO: UCP2009-1813 DRWN:SDANIELLEY 2009/07/17 CHKD:SMART 2009/07/24 APPR:SMILLER 2009/07/24	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
					DRAWN BY ELO	DATE 1998/05/21	TITLE SALES ASSY , HDM BACKPLANE POWER MODULE (PRESSFIT)				
					CHECKED BY SMR	DATE 1998/05/21					
					APPROVED BY CAB	DATE 1998/05/21					
			ANGULAR ±1/2°		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SDA-73656-*00*				
					SIZE B		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

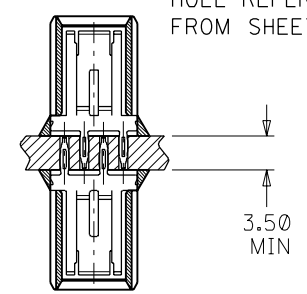


73656-100* 73656-200*

DATE CODE AND
PART NUMBER ON
THIS SURFACE OR
SURFACE OPPOSITE.

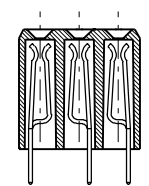
MIDPLANE OPTION

ASSEMBLY NUMBER	FINISH (SEE SHT 1)
73656-1000	SEE NOTE 2. (GOLD TAILS)
73656-2000	
73656-1001	SEE NOTE 3. (TIN/LEAD TAILS)
73656-2001	

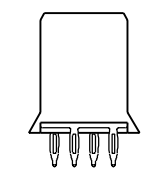
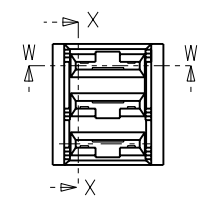
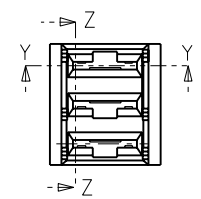


BACK-TO-BACK
MOUNTING APPLICATION

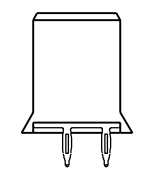
USE BACKPLANE MODULE
HOLE REFERENCE PATTERN
FROM SHEET 1



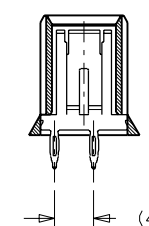
SECTION X-X
SECTION Z-Z
ROTATED 90° CW



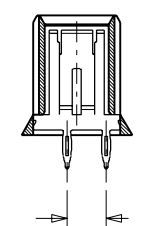
73656-200*



73656-100*



SECTION: Y-Y



SECTION: W-W

F
E
D
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A

F
E
D
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B
A

				D		SEE SHEET 1	DIMENSIONS SHOWN (METRIC) INCH		REVISE ONLY ON CAD SYSTEM	
				B		SEE SHEET 1	UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°		TITLE SALES ASSY, HDM BACKPLANE POWER MODULE (PRESS FIT)	
				A		SEE SHEET 1	3 PLACE ± N/A --- 2 PLACE ± N/A ± --- 1 PLACE --- ± ---		MOLEX INCORPORATED LISLE, ILL. 60532 U.S.A.	
				LTR.		REVISIONS	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		PART NO. SEE CHART	
							DRWG. BY ELO CHK'D. BY SMR		SHEET NO. 2	
							APP'D. BY CAB SCALE 2 : 1		DATE 98/05/21	
							FILE NAME S73656X2 DGN		DIV. DA	
							THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.		SIZE B	

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<http://moschip.ru/get-element>

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Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

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На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

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